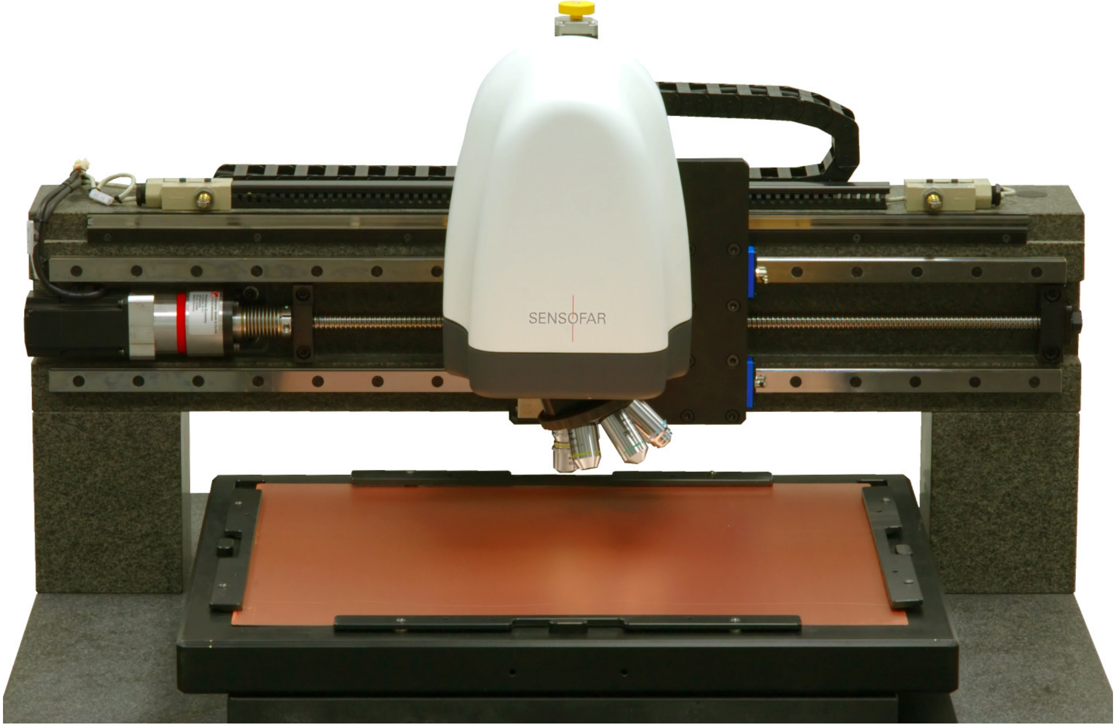
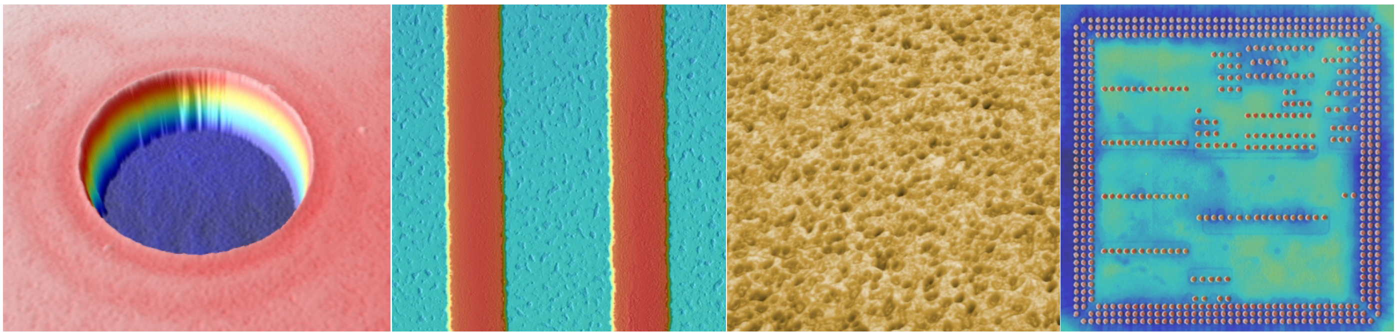
PLμ
CP series

SENSOFAR

PLμ CP Series
Control of Production Optical Profilers



Large sample size: Up to 610 x 610 mm
Fast and reliable Non-contact 3D inspection
Fully automated acquisition and analysis
Highest throughput for in-line process control



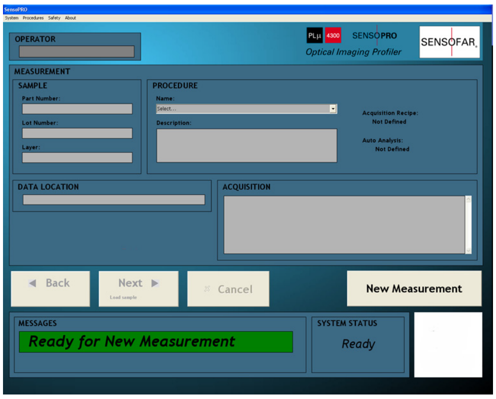
Optical Profiler
Control of Production Series

PLμ CP

Control of production PL*μ* series have been specially designed for fast characterization of large samples like panels containing PCBs, vias, flip-chip and traces analysis. Based on the well proven Sensofar's optical profiling technology, you can now profile any surface with Interferometry techniques (PL*μ* 4300 CP) or the combination of both Confocal and Interferometry techniques (PL*μ* 2300 CP).

Non-Contact 3D Profiling

Confocal. Highest lateral resolution (0.1*μ*m) and highest local slopes (up to 70º) ideal for wall angle analysis.
PSI and VSI. Provides the highest vertical resolution (sub-nanometer resolution) and the fastest acquisition time.
Spectroscopic reflectometer. Integrated technology that can be the perfect option for thickness of transparent materials with sub-nanometer resolution.



Acquisition Recipe: Not Defined

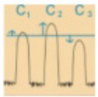
Auto Analysis: Not Defined

Ready for New Measurement

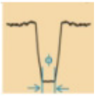
Ready

IC Packaging module

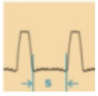
The PL*μ* CP Series are flexible tools tailored to the IC Packaging industry. Accurate measurements of BGA bumps, vias, copper traces, solder resistance and anchor regions are provided to help you improve your production process.



BGA
- Number of balls
- Position, height and diameter for each ball
- Flip-Chip coplanarity



Via and SR/Open
- Top and bottom diameter
- Via elipticity and height
- Top surface and bottom via/SR roughness



Traces
- Trace height
- Trace and space width
- Trace and space roughness

Others
- Copper and Anchor

Distributor

New stage design

Based on a gantry granite platform, the stage is able to accommodate up to 610x610mm samples. Multiple fixture and holder types offer wide range of possibilities to inspect different samples: from large panels (like PCBs) to several flip-chips, allowing the system to inspect and automatically report Via, Anchor, S/R and Trace dimensions.

Data acquisition and analysis

The well-known and established Sensofar's software SensoSCAN®, allows the inspection of the surface, data acquisition and analysis. Fully integrated recipes for data acquisition on multiple places, autofocus, auto lighting and auto referencing functions!
SensoPRO® analysis software is used to fully automate the production sequence. Loading, executing an acquisition recipe and performing online data analysis thus providing fast and reliable statistics on the quality of the production process.

Specifications[1]

Measurement Capability:	Image, 3D-Topograpy, Profiles, Coordinate, Thickness, Zoom function, Filters, etc
Stage XY:	610 x 610 mm
Vertical Resolution:	< 0.1 nm
Step Height Accuracy:	0.8 %
Step Height Repeatability:	< 0.1 %
Footprint:	WxDxH: 106 x 139 x 135 cm
Weight:	2500 kg

---

[1] Based on PL*μ* 4300 CP

SENSOFAR®

Sensofar-Tech, S.L.
Ctra. N-150, km. 14,5
Mòdul TR20 - IPCT
E-08227 Terrassa
T: +34 93 739 89 45
F: +34 93 786 01 16
info@sensofar.com
www.sensofar.com